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UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICATION SERIAL NO. 09/388,826
FILING DATE September 1, 1999
INVENTOR Weimin Li, et al.
ASSIGNEE Micron Technology, Inc.
GROUP ART UNIT 2813
EXAMINER E. Kielin
ATTORNEY'S DOCKET NO. MI22-1208
TITLE: Low k Interlevel Dielectric Layer Fabrication Methods

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References -See Attached Form PTO-1449

The Examiner's attention is directed to the references which are listed on the attached form PTO-1449, a copy of which is attached. No admission is made regarding whether the submitted references are prior art.

Citation of the referenced is respectfully requested.

Respectfully submitted,

Dated:

5-22-03

By

D. Brent Kenady
Reg. No. 40,045

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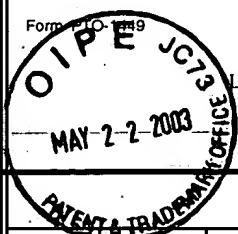
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Sheet 1 of 1

Form 10-199 		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. M122-1208		SERIAL NO. 09/388,826		
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)								
APPLICANT Weimin Li, et al.						FILING DATE September 1, 1999		
						GROUP 2813		
U.S. PATENT DOCUMENTS								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA	4,755,478	07/05/1988	ABERNATHY, ET AL.	437	41		
	AB	4,870,470	09/26/1989	BASS, JR., ET AL.	357	23.5		
	AC	5,312,768	05/17/1994	GONZALEZ	437	40		
	AD	5,439,838	08/08/1995	YANG	437	43		
	AE							
	AF							
	AG							
	AH							
	AI							
	AJ							
	AK							
	AL							
FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AM							
	AN							
	AO							
	AP							
	AQ							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
	AR							
	AS							
	AT							
EXAMINER				DATE CONSIDERED				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								